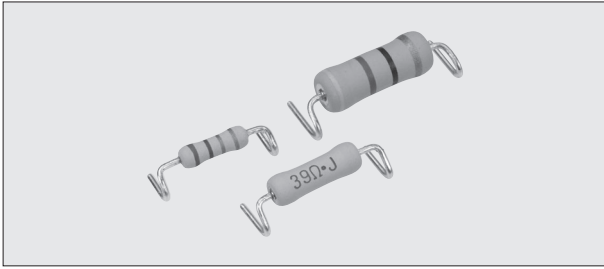
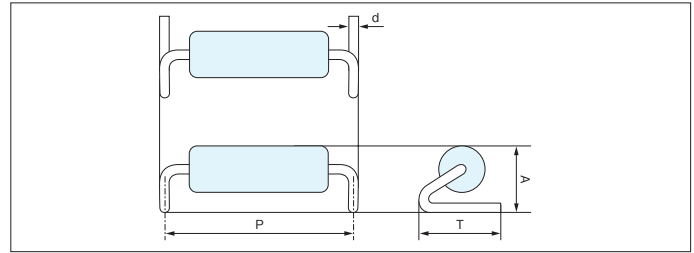


Surface mounted device style lead forming



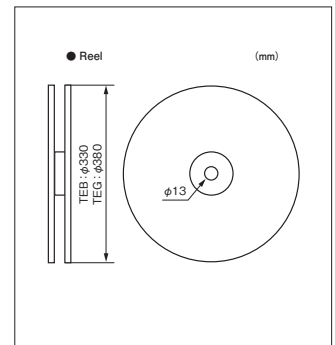
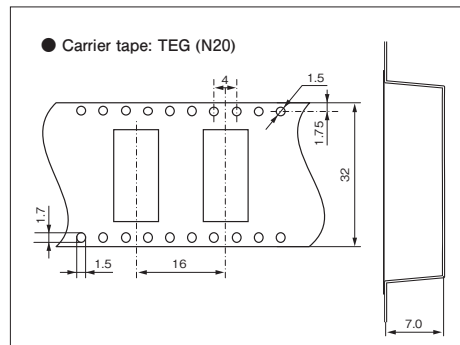
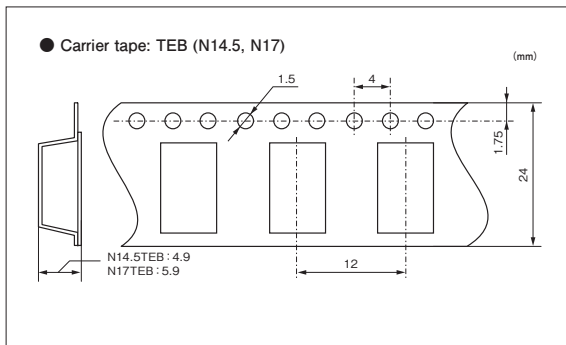
Forming style



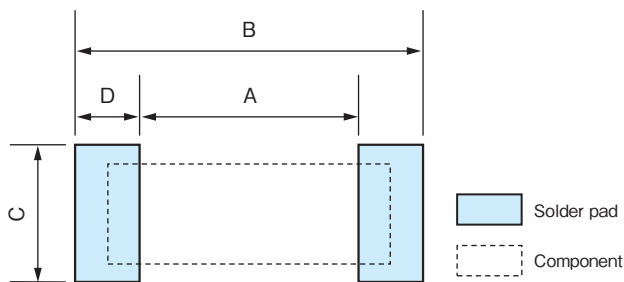
Ratings

Type	Forming Type Name	Carrier Tape	Forming Dimension (mm)				Q'ty/Reel (pcs)	Weight (g)	
			P±1	T	A±0.5	d		Reel	NET/1000pcs
MOS(X)1	N14.5	TEB	14.5	5.0±0.5	4.8	0.8	1,000	700	350
MOS(X)2 SPR(X)2 RCR75 CW2	N17	TEB	17.0	6.0±0.5	5.8	0.8	1,000	900	600
MOS(X)3 SPR(X)3 RCR100 CW3	N20	TEG	20.0	7.5±1	6.5	0.8	900	1,800	1,400

Packaging Specifications



Recommended Pad Dimensions



Type	Forming Type Name	Pad Dimension (mm)			
		A	B	C	D
MOS(X)1	N14.5TEB	12.5	16.5	7.0	2.0
MOS(X)2 SPR(X)2 RCR75 CW2	N17TEB	14.6	19.4	8.0	2.4
MOS(X)3 SPR(X)3 RCR100 CW3	N20TEG	17.6	22.4	9.5	2.4

● Need a dedicated nozzle for automatic mounting. Please inquire to us before use.